

Silicon NPN Triple Diffused Character Display Horizntal Deflection Output

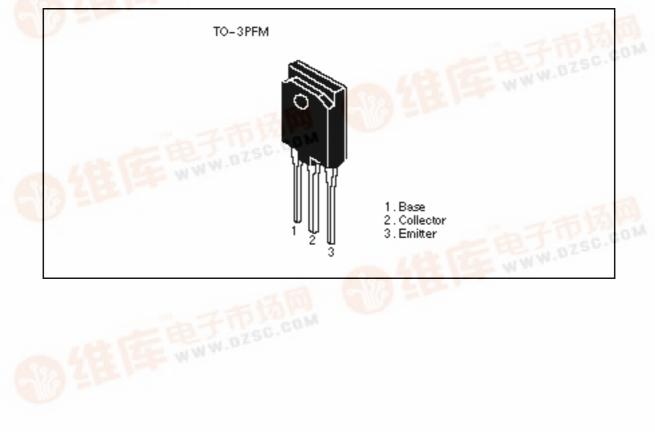


3rd. Edition December 1997 Target Specification

Features

- High breakdown voltage $V_{CBO} = 1500 \text{ V}$
- High speed switching
- $t_f = 0.15 \ \mu sec \ (typ.) at f_H = 64 kHz$
- Isolated package TO-3PFM

Outline





2SC5461

Absolute Maximum Ratings (Ta = 25° C)

Item	Symbol	Ratings	Unit	
Collector to base voltage	V _{CBO}	1500	V	
Collector to emitter voltage	V _{CEO}	700	V	
Emitter to base voltage	V _{EBO}	6	V	
Collector current	Ι _c	15	А	
Collector peak current	İ _{c(peak)}	30	А	
Collector power dissipation	P _C ^{Note1}	50	W	
Junction temperature	Tj	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

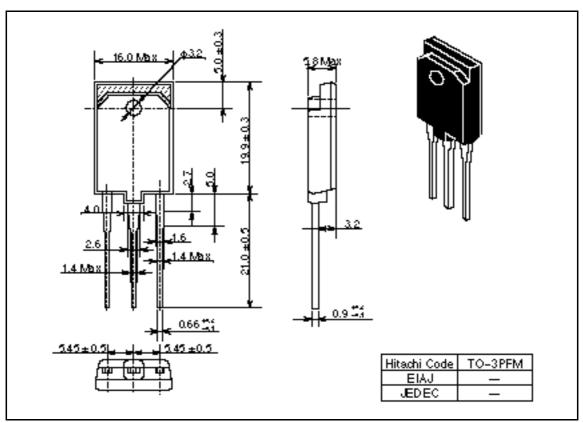
Note: 1. Value at $Tc = 25^{\circ}C$

Electrical Characteristics (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	700	—	—	V	$I_c = 10$ mA, $R_{BE} =$
Emitter to base breakdown voltage	$V_{(\text{BR})\text{EBO}}$	6	_	_	V	$I_{\rm E} = 10 {\rm mA}, \ I_{\rm C} = 0$
Collector cutoff current	I _{CES}	_	_	500	μA	$V_{ce} = 1500V, R_{be} = 0$
DC current transfer ratio	h_{FE1}	10	_	40		$V_{ce} = 5 V$, $I_c = 1A$
DC current transfer ratio	h_{FE2}	3.5	_	6.5		$V_{ce} = 5 V, I_{c} = 8A$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$		_	5	V	$I_{\rm C} = 10A, I_{\rm B} = 3A$
Base to emitter saturation voltage	$V_{\text{BE(sat)}}$	_	_	1.5	V	$I_{\rm C} = 10A, I_{\rm B} = 3A$
Fall time	t _f		0.2	0.4	μs	$I_{CP} = 7A, I_{B1} = 2.8A$ $f_{H} = 31.5 \text{kHz}$
Fall time	t _f	_	0.15	_	μs	I _{CP} = 7A, I _{B1} = 1.8A f _H = 64kHz

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Package Dimensions



Unit: mm

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Hitachi, Ltd.

Semiconductor & IC DW. Nepton Bidg., 2-5-2, Otte-mediti, Chiyoda-ku, Tokyo 100, Jepan Tet Tokyo (03, 3270-2111 Fax: (03, 3270-5109

For Authorin formation write to : Histohi America, Ud Semiconductor & IC Div. 2000 Sierre Point Ferkway Briebene, CA. 94005-4835 U S.A Tet 445-589-8300 Fax: 445-583-4207

Hitschi Burope GmbH Bedronic Components Group Cartinertal Burope Darnscher Streife 3 Des5522 Feldkirchen Minichen Tet 083-9 91 80-0 Feix 083-9 91 80-0 Hitschi Europe Ltd. Bectronic Components Div. Northern Burge Hesdguerters Whitebrook Park Lower Cook hem Rosd Meidenhesd Berkshire SLESYA Urited Kingdon Tet 0528-555000 Fex 0528-778322 Hitschi Asia Pta, Ltd +5 Collyer Quay #20-00 Hitschi Tower Snappore 0104 Tet 535-2100 Fax 535-1533

Hitschi Asia (Hong Kong) Ltd. Unit 705, North Towar, World Finance Cantre, Herbour City, Carton Road Taim She Tau, Kowloon Hong Kong Tet 27359218 Fax: 27306074

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